

Notice of References Cited	Application/Control No. 10/724,325	Applicant(s)/Patent Under Reexamination CRUZ ET AL.	
	Examiner Paul D. Kim	Art Unit 3729	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,581,278	06-2003	Kay, Yuen Yew	29/830
*	B	US-6,359,336	03-2002	Cantillep et al.	257/726
*	C	US-6,284,572	09-2001	Cantillep et al.	438/112
*	D	US-5,695,331	12-1997	Nutter et al.	432/253
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	JP 2001148390 A	05-2001	Japan	KURATOMI et al.	
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Advanced module packaging method"; Salmon, P.C.; Quality Electronic Design, 2003. Proceedings. Fourth International Symposium on 24-26 March 2003; Pages:223 - 228.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.